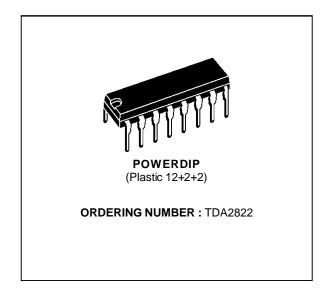


## **TDA2822**

## **DUAL POWER AMPLIFIER**

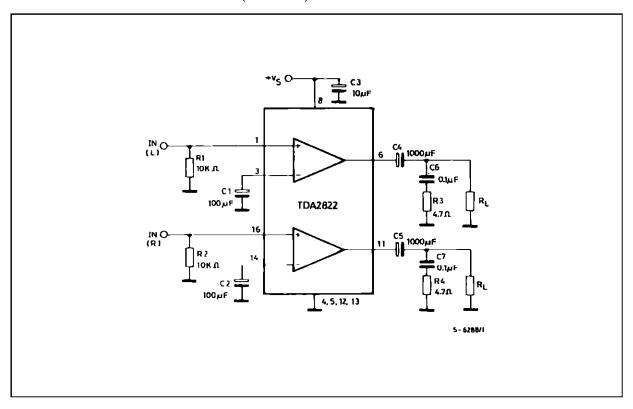
- SUPPLY VOLTAGE DOWN TO 3 V
- LOW CROSSOVER DISTORSION
- LOW QUIESCENT CURRENT
- BRIDGE OR STEREO CONFIGURATION



#### **DESCRIPTION**

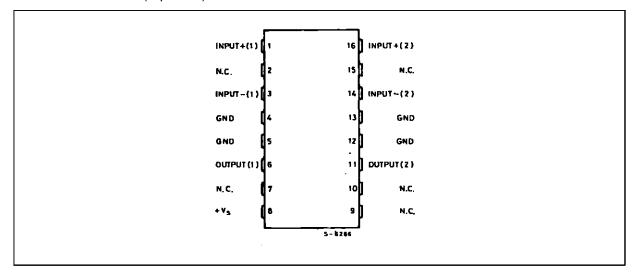
The TDA2822 is a monolithic integrated circuit in 12+2+2 powerdip, intended for use as dual audio power amplifier in portable radios and TS sets.

#### **TYPICAL APPLICATION CIRCUIT (STEREO)**

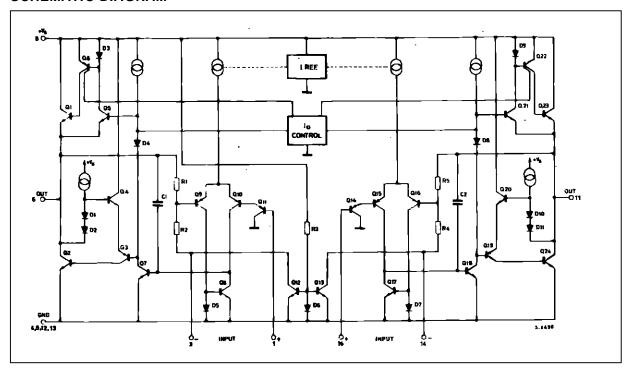


March 1995 1/11

#### PIN CONNECTION (top view)



#### **SCHEMATIC DIAGRAM**



#### **ABSOLUTE MAXIMUM RATINGS**

| Symbol                            | Parameter  | Value       | Unit   |
|-----------------------------------|--|-------------|--------|
| Vs                                | Supply Voltage   | 15          | V      |
| lo                                | Output Peak Current  | 1.5         | Α      |
| P <sub>tot</sub>                  | Total Power Dissipation at $T_{amb}$ = 50 °C at $T_{case}$ = 70 °C | 1.25<br>4   | W<br>W |
| T <sub>stg</sub> , T <sub>j</sub> | Storage and Junction Temperature                                   | - 40 to 150 | °C     |



#### THERMAL DATA

| Symbol                 | Parameter                               | Value | Unit |
|------------------------|---|-------|------|
| R <sub>th j-amb</sub>  | Thermal Resistance Junction-ambient Max | 80    | °C/W |
| R <sub>th j-case</sub> | Thermal Resistance Junction-pins Max    | 20    | °C/W |

# **ELECTRICAL CHARACTERISTICS** (Vs = 6 V, $T_{amb}$ = 25 °C, unless otherwise specified) STEREO (test circuit of fig. 1)

| Symbol         | Parameter                      | Test Condition   | Min.        | Тур.                | Max. | Unit        |
|----------------|--------------------------------|--|-------------|---------------------|------|-------------|
| Vs             | Supply Voltage                 |  | 3           |                     | 15   | V           |
| Vc             | Quiescent Output Voltage       | V <sub>s</sub> = 9 V<br>V <sub>s</sub> = 6 V   |             | 4<br>2.7            |      | V<br>V      |
| l <sub>d</sub> | Quiescent Drain Current        |  |             | 6                   | 12   | mA          |
| lb             | Input Bias Current             |  |             | 100                 |      | nA          |
| Po             | Output Power<br>(each channel) | $ \begin{aligned} &d = 10 \ \% & f = 1 \ \text{kHz} \\ &V_s = 9 \ V & R_L = 4 \ \Omega \\ &V_s = 6 \ V & R_L = 4 \ \Omega \\ &V_s = 4.5 \ V & R_L = 4 \ \Omega \end{aligned} $ | 1.3<br>0.45 | 1.7<br>0.65<br>0.32 |      | W<br>W<br>W |
| $G_v$          | Closed Loop Voltage Gain       | f = 1 kHz  | 36          | 39                  | 41   | dB          |
| Ri             | Input Resistance               | f = 1 kHz  | 100         |                     |      | kΩ          |
| <sup>e</sup> N | Total Input Noise              | $R_s$ = 10 k $\Omega$<br>B = 22 Hz to 22 kHz<br>Curve A  |             | 2.5<br>2            |      | μV<br>μV    |
| SVR            | Supply Voltage Rejection       | f = 100 Hz   | 24          | 30                  |      | dB          |
| CS             | Channel Separation             | $R_g = 10 \text{ k}\Omega \text{ f} = 1 \text{ kHz}$   |             | 50                  |      | dB          |

### BRIDGE (test circuit of fig. 2)

| Vs             | Supply Voltage           |  | 3          |                  | 15 | V           |
|----------------|--------------------------|--|------------|------------------|----|-------------|
| $I_d$          | Quiescent Drain Current  | R <sub>L</sub> = ∞   |            | 6                | 12 | mA          |
| Vos            | Output Offset Voltage    | $R_L = 8 \Omega$   |            | 10               | 60 | mV          |
| I <sub>b</sub> | Input Bias Current       |  |            | 100              |    | nA          |
| Po             | Output Power             | $ d = 10 \%  f = 1 \text{ kHz} $ $ V_s = 9 \text{ V}  R_L = 8 \Omega $ $ V_s = 6 \text{ V}  R_L = 8 \Omega $ $ V_s = 4.5 \text{ V}  R_L = 4 \Omega $ | 2.7<br>0.9 | 3.2<br>1.35<br>1 |    | W<br>W<br>W |
| d              | Distortion (f = 1 kHz)   | $R_L = 8 \Omega$ $P_o = 0.5 W$   |            | 0.2              |    | %           |
| G <sub>v</sub> | Closed Loop Voltage Gain | f = 1 kHz  |            | 39               |    | dB          |
| Ri             | Input Resistance         | f = 1 kHz  | 100        |                  |    | kΩ          |
| <sup>e</sup> N | Total Input Noise        | $R_s$ = 10 k $\Omega$<br>B = 22 Hz to 22 kHz<br>Curve A  |            | 3<br>2.5         |    | μV<br>μV    |
| SVR            | Supply Voltage Rejection | f = 100 Hz   |            | 40               |    | dB          |

Figure 1: Test Circuit (stereo).

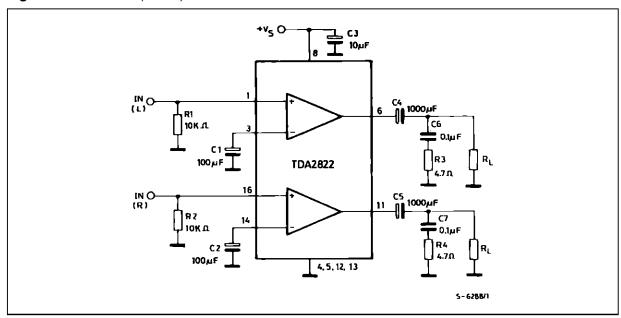


Figure 2: P.C. Board and Components Layout of the Circuit of Figure 1 (1:1 scale).

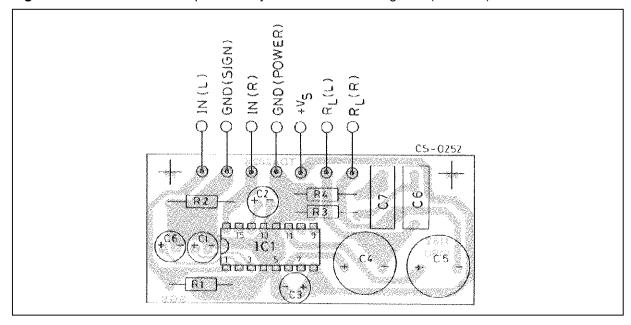


Figure 3: Test Circuit (bridge).

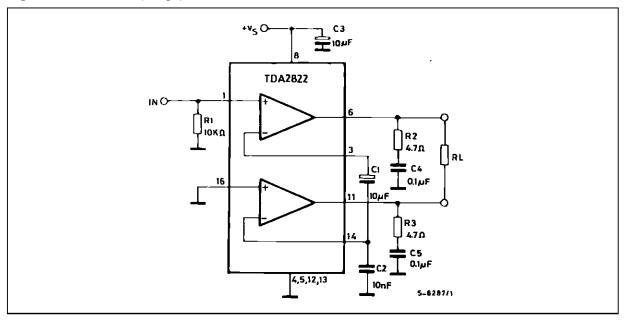
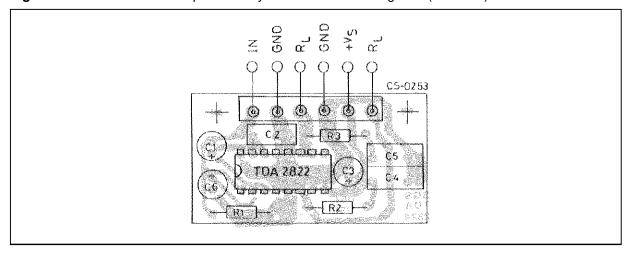
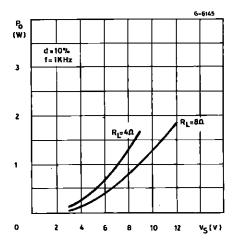


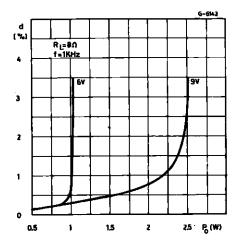
Figure 4: P.C. Board and Components Layout of the Circuit of Figure 3 (1:1 scale).



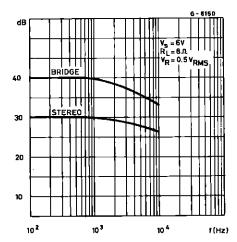
**Figure 5 :** Output Power vs. Supply Voltage (Stereo).



**Figure 7 :** Distorsion vs. Output Power (Bridge).



**Figure 9 :** Supply Voltage Rejection vs. Frequency.



**Figure 6 :** Output Power vs. Supply Voltage (Bridge).

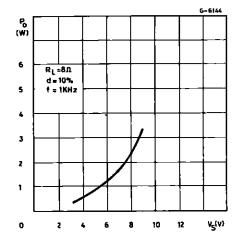


Figure 8: Distorsion vs. Output Power (Bridge).

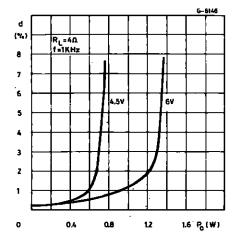
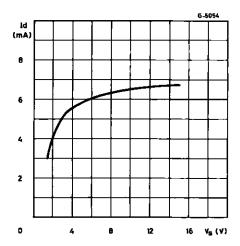
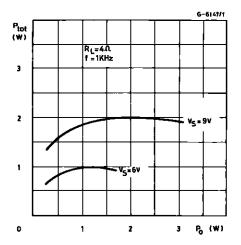


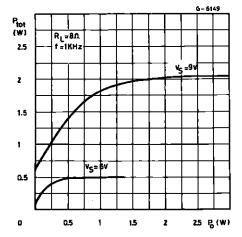
Figure 10: Quiescent Current vs. Supply Voltage.



**Figure 11 :** Total Power Dissipation vs. Output Power (Stereo).



**Figure 13 :** Total Power Dissipation vs. Output Power (Bridge).



**Figure 12 :** Total Power Dissipation vs. Output Power (Bridge).

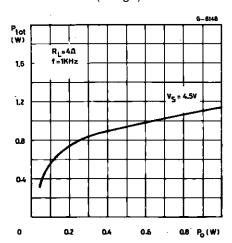
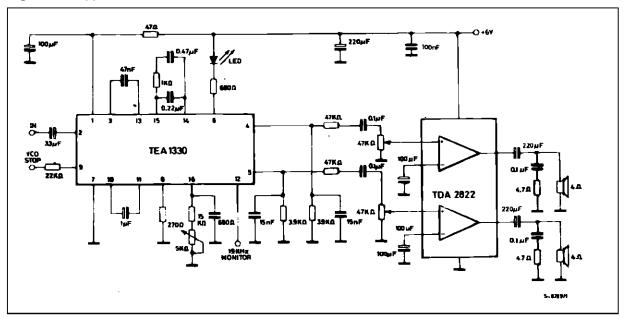


Figure 14: Application Circuit for Portable Radios.

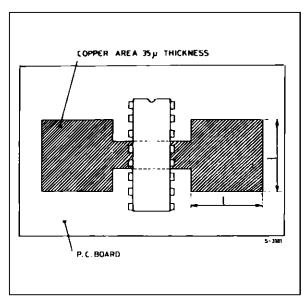


#### MOUNTING INSTRUCTION

The  $R_{th\,j-amb}$  of the TDA2822 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (Figure 15) or to an external heatsink (Figure 16).

The diagram of Figure 17 shows the maximum dissipable power  $P_{tot}$  and the  $R_{th\ j-amb}$  as a function of the side " $\partial$ " of two equal square copper areas having a thickness of  $35\,\mu$  (1.4 mils).

**Figure 15 :** Example of P.C. Board Copper Area which is used as Heatsink.



During soldering the pins temperature must not exceed 260  $^{\circ}$ C and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 16: External Heatsink Mounting Example.

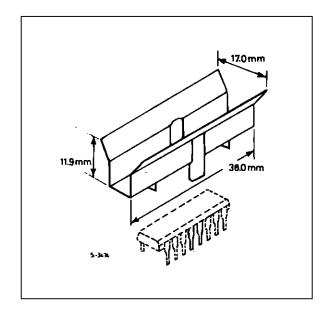


Figure 6 : Maximum Dissipable Power and Junction to Ambient Thermal Resistance vs. Side "∂".

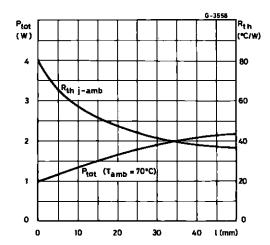
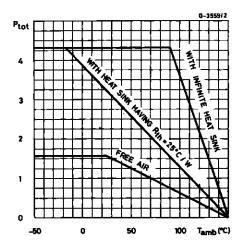
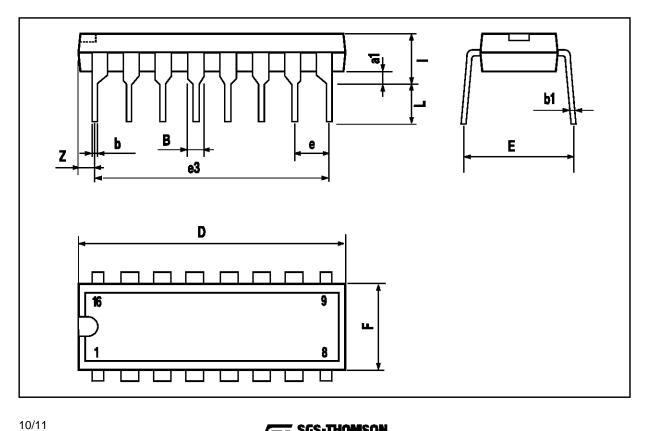


Figure 7: Maximum Allowable Power Dissipation vs. Ambient Temperature.



## **POWERDIP 16 PACKAGE MECHANICAL DATA**

| DIM.  | mm   |       |      | inch  |       |       |  |
|-------|------|-------|------|-------|-------|-------|--|
| Diwi. | MIN. | TYP.  | MAX. | MIN.  | TYP.  | MAX.  |  |
| a1    | 0.51 |       |      | 0.020 |       |       |  |
| В     | 0.85 |       | 1.40 | 0.033 |       | 0.055 |  |
| b     |      | 0.50  |      |       | 0.020 |       |  |
| b1    | 0.38 |       | 0.50 | 0.015 |       | 0.020 |  |
| D     |      |       | 20.0 |       |       | 0.787 |  |
| E     |      | 8.80  |      |       | 0.346 |       |  |
| е     |      | 2.54  |      |       | 0.100 |       |  |
| e3    |      | 17.78 |      |       | 0.700 |       |  |
| F     |      |       | 7.10 |       |       | 0.280 |  |
| I     |      |       | 5.10 |       |       | 0.201 |  |
| L     | _    | 3.30  |      |       | 0.130 |       |  |
| Z     |      |       | 1.27 |       |       | 0.050 |  |



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